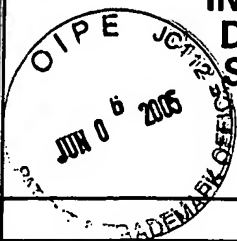


INFORMATION DISCLOSURE STATEMENT



SHEET 1 OF 1

Complete if known

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First Named Inventor: Steinberg

Group Art Unit: 1775

Examiner Name: Stephen J. Stein

Attorney Docket Number: R&H 03-19

UNITED STATES PATENT DOCUMENTS

EXAMINER'S INITIALS	CITE NO.	PATENT NUMBER	ISSUE DATE MM-DD-YYYY	FIRST NAMED INVENTOR
		4810557	03/07/1989	Blonder
		4837129	06/06/1989	Frisch et al.
		4863560	09/05/1989	Hawkins
		4904036	02/27/1990	Blonder
		4938841	07/03/1990	Shahar et al.
		4957592	09/18/1990	O'Neill
		5338400	08/16/1994	Jerman
		5478438	12/26/1995	Nakanishi et al.
		5479426	12/26/1995	Nakanishi et al.
		5611006	03/11/1997	Tabuchi
		5911021	06/08/1999	MacDonald et al.
		6132107	10/17/2000	Morikawa
		6187515	02/13/2001	Tran et al.
		6257772	07/10/2001	Nakanishi et al.
		6553173	04/22/2003	Goto
		6567590	05/20/2003	Okada et al.
		US 2002/0195417	12/26/2002	Steinberg
		US 2003/0020130	01/30/2003	Steinberg et al.
		US 2003/0067049	04/10/2003	Steinberg et al.
		US 2003/0021572	01/30/2003	Steinberg

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	CITE NO.	DOCUMENT NUMBER	COUNTRY OR REGION	DATE OF PUBLICATION MM-DD-YYYY	FIRST NAMED INVENTOR OR APPLICANT

OTHER PRIOR ART - NON-PATENT DOCUMENTS

EXAMINER'S INITIALS	CITE NO.	Include name of the author (in Capital Letters), title of the article (when appropriate), title of the item(book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published
		Nijdam, et al. "Etching of silicon in alkaline solutions: a critical look at the {111} minimum," MESA
		Oosterbroek, et al. "New design methodologies in <111> oriented silicon wafers," MESA
		Suchtelen, et al. "Simulation of Anisotropic Wet-Chemical Etching Using a Physical Model," MESA

EXAMINER'S SIGNATURE	DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP §609. Draw a line through citation if citation not in conformance and reference not considered. Include a copy of this form with next communication to applicant.